

L Number	Hits	Search Text	DB	Time stamp
1	4963	TFT and ((wir\$ or cathode or electrode) same (copper or Cu or silver or Ag or gold or Au or aluminum or Al or nickel or Ni))	USPAT	2004/05/12 16:18
2	725	TFT and ((wir\$ or cathode or electrode) same (copper or Cu or silver or Ag or gold or Au or aluminum or Al or nickel or Ni) same laminat\$)	USPAT	2004/05/12 16:18
-	169	((light same emitting) same wiring) and 313/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 17:34
-	113	((light same emitting) same wiring) and 313/\$.ccls.) and (film same (copper or Cu or silver or Ag or gold or Au or aluminum or Al or nickel or Ni))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 08:54
-	72	((light same emitting) same wiring) and 313/\$.ccls.) and (wiring same (copper or Cu or silver or Ag or gold or Au or aluminum or Al or nickel or Ni))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 08:55
-	4	((light same emitting) same wiring) and 313/\$.ccls.) and (via adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 10:38
-	299	(313/500).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 10:38
-	2919	(313/500-512).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 10:39
-	96	((313/500-512).CCLS.) and ((light same emitting) same wiring) and 313/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/15 10:40
-	5	("3219865").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 17:32
-	1	("3219865").PN.	USPAT	2003/07/30 17:32
-	0	("3219865").PN.) and wir\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 17:33
-	1	3219865.pn. and wir\$	USOCR	2003/07/30 17:33
-	210	((light same emitting) same wiring) and 313/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 17:34
-	147	((light same emitting) same wiring) and 313/\$.ccls.) and (wir\$ same substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 17:50
-	1	09/732049	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 17:50

-	1	09/732049 and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 17:52
-	33900	(printed adj wiring adj board) or PWB	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 17:53
-	62	((printed adj wiring adj board) or PWB) and 313/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/30 17:53
-	26	((printed adj wiring adj board) or PWB) and 313/\$.ccls.	USPAT	2003/07/30 17:53
-	1	("5435937").PN.	USPAT	2003/07/31 08:40
-	531	(313/509).CCLS.	USPAT	2003/08/01 14:13
-	736	substrate same wir\$ same phosphor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 08:54
-	108	(substrate same wir\$ same phosphor) and 313/\$.ccls.	USPAT	2003/07/31 08:55
-	62	(substrate same wir\$ same phosphor same connect\$) and 313/\$.ccls.	USPAT	2003/07/31 08:59
-	2	("3571647").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/31 08:57
-	9	(substrate same wir\$ same phosphor same connect\$ same parallel) and 313/\$.ccls.	USPAT	2003/07/31 09:32
-	5331	(substrate same wir\$ same resin)	USPAT	2003/08/01 11:59
-	178	(substrate same wir\$ same resin) and (light-emitting)	USPAT	2003/08/01 12:01
-	4	(substrate same wir\$ same resin same (via with hole)) and (light-emitting)	USPAT	2003/08/01 12:01
-	363	(substrate same (electrode or wir\$) same (via adj hole) same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 13:54
-	3	(substrate same (electrode or wir\$) same (via adj hole) same resin same (lumin\$ or phosphor\$ or fluores\$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 14:02
-	34	(substrate same (electrode or wir\$) same (via adj hole) same (lumin\$ or phosphor\$ or fluores\$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 14:12
-	26793879	JP "08139458" A	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/01 14:13
-	531	(313/509).CCLS.	USPAT	2003/08/01 14:15
-	114	((313/509).CCLS.) and via	USPAT	2003/08/01 14:24
-	1	("4340840").PN.	USPAT	2003/08/01 14:30
-	0	(gate adj control\$ adj wiring) and 313/\$.ccls.	USPAT	2003/08/01 14:32
-	10	(gate with control\$ with wiring) and 313/\$.ccls.	USPAT	2003/08/01 14:32
-	7059	substrate with fill\$ with resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 19:16

-	7456	substrate with fill\$ with resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 19:16
-	0	(substrate with fill\$ with resin with wire) and 313/\$.ccls.	USPAT	2003/08/19 19:17
-	23	(substrate with fill\$ with resin) and 313/\$.ccls.	USPAT	2003/08/21 08:40
-	0	substrate same (gate with control) same (gate with auxillary)	USPAT	2003/08/19 19:30
-	54	substrate same (gate with control) same (gate with auxiliary)	USPAT	2003/08/19 19:30
-	0	(substrate same (gate with control) same (gate with auxiliary)) and resin	USPAT	2003/08/19 19:31
-	192	(gate with control\$ with wiring) and clock	USPAT	2003/08/21 06:26
-	27	((gate with control\$ with wiring) and clock) and resin	USPAT	2003/08/21 06:28
-	0	"09732049"	US-PGPUB	2003/08/21 06:36
-	1	("3219865").PN.	USPAT	2003/08/21 06:36
-	3	(substrate with fill\$ with resin) and 315/\$.ccls.	USPAT	2003/08/21 07:29
-	1224	(313/495-497).CCLS.	USPAT	2003/08/21 08:40
-	220	((313/495-497).CCLS.) and (layer\$ with wir\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/21 08:54
-	35	((((313/495-497).CCLS.) and (layer\$ with wir\$)) and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/21 09:16
-	0	5703435.pn. and gate	USPAT	2003/08/21 09:15
-	6	((((313/495-497).CCLS.) and (layer\$ with wir\$)) and (spacer same resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/21 09:21
-	21	07/851701	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/21 09:21
-	0	07/851701.ap.	USPAT	2003/08/21 09:21
-	0	"07/851701".ap.	USPAT	2003/08/21 09:22
-	21	07/851701	USPAT	2003/08/21 09:22
-	536	(313/509).CCLS.	USPAT	2003/08/21 10:08
-	3	((313/509).CCLS.) and (via adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/21 10:08
-	1224	(313/495-497).CCLS.	USPAT	2003/08/21 10:09
-	5	((313/495-497).CCLS.) and (via adj hole)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/21 10:12
-	18835	via adj hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/21 10:12
-	18835	via adj hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/21 10:12
-	7802	via adj hole	USPAT	2003/08/21 10:12
-	2492	(via adj hole) same substrate	USPAT	2003/08/21 10:13
-	690	((via adj hole) same substrate) and resin	USPAT	2003/08/21 10:13
-	19	((((via adj hole) same substrate) and resin) and (EL or electroluminescent)	USPAT	2003/08/22 08:40

-	1	("5965981").PN.	USPAT	2003/08/22 08:33
-	15	((via adj hole) same substrate) and resin) and (EL or electroluminescent) and wir\$	USPAT	2003/08/22 09:54
-	220	substrate same (EL or electroluminescent) same wir\$	USPAT	2003/08/22 09:55
-	84	substrate same (EL or electroluminescent) same wir\$ and 313/\$.ccls.	USPAT	2003/08/22 09:55
-	0	"09/732049" and 18A	US-PGPUB	2004/05/04 15:01
-	1	"09/732049" and "18"	US-PGPUB	2004/05/04 15:01
-	447344	"09/732049" and Fig. "18"	US-PGPUB	2004/05/04 15:02
-	0	"09/732049" and "Fig. 18"	US-PGPUB	2004/05/04 15:02
-	0	"09/732049" and "Fig.18"	US-PGPUB	2004/05/04 15:02
-	0	"09/732049" and "Fig.18A"	US-PGPUB	2004/05/04 15:02
-	0	"09/732049" and "Fig. 18A"	US-PGPUB	2004/05/04 15:02
-	1	"09/732049"	US-PGPUB	2004/05/04 15:02
-	1	"09/732049"	US-PGPUB	2004/05/06 07:52
-	1	"09/732049" and "current supply line"	US-PGPUB	2004/05/06 07:54
-	1	"09/732049" and via	US-PGPUB	2004/05/06 07:54
-	0	"09/732049" and (via same TFT)	US-PGPUB	2004/05/06 08:13
-	1	"09/732049" and "metallic film"	US-PGPUB	2004/05/06 08:13
-	1	"09/732049" and "main component"	US-PGPUB	2004/05/06 08:36
-	1	"09/732049" and auxiliary	US-PGPUB	2004/05/06 08:36
-	1	"09/732049"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 11:07
-	1	"09/732049" and gate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 11:09
-	1	"09/732049" and clock	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 11:10
-	1	"09/732049" and "gate control wiring"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 11:14
-	773	(313/500,505,498).CCLS.	USPAT	2004/05/07 07:26
-	24	TFT and PWB	USPAT	2004/05/06 12:20
-	1	"6312836".PN.	USPAT	2004/05/06 14:38
-	773	(313/500,505,498).CCLS.	USPAT	2004/05/07 09:45
-	62	((313/500,505,498).CCLS.) and (TFT or thin\$film\$transistor)	USPAT	2004/05/07 07:52
-	1	("6215244").PN.	USPAT	2004/05/07 07:52
-	1	((("6215244").PN.) and (copper or silver or gold or aluminum or nickel)	USPAT	2004/05/07 07:55
-	1404	(conductive adj paste) with (copper or silver or gold or aluminum or nickel)	USPAT	2004/05/07 07:55
-	63	((conductive adj paste) with (copper or silver or gold or aluminum or nickel)) and 313/\$.ccls.	USPAT	2004/05/07 07:56
-	6	((((conductive adj paste) with (copper or silver or gold or aluminum or nickel)) and 313/\$.ccls.) and TFT	USPAT	2004/05/07 07:56
-	773	(313/500,505,498).CCLS.	USPAT	2004/05/11 07:14
-	1905	(315/169.1,169.2,169.3).CCLS.	USPAT	2004/05/07 09:45
-	1792	((315/169.1,169.2,169.3).CCLS.) not ((313/500,505,498).CCLS.)	USPAT	2004/05/07 09:47
-	153	((((315/169.1,169.2,169.3).CCLS.) not ((313/500,505,498).CCLS.)) and (TFT or thin\$film\$transistor)	USPAT	2004/05/07 09:47
-	171	((((315/169.1,169.2,169.3).CCLS.) not ((313/500,505,498).CCLS.)) and (TFT or thin\$film\$transistor)	USPAT	2004/05/07 09:48
-	2451	(313/501,502,503,504,506-512).CCLS.	USPAT	2004/05/11 07:14
-	775	(313/500,505,498).CCLS.	USPAT	2004/05/11 07:14
-	2027	((313/501,502,503,504,506-512).CCLS.) not ((313/500,505,498).CCLS.)	USPAT	2004/05/11 07:15

-	110	((313/501,502,503,504,506-512).CCLS.) not	USPAT	2004/05/11 07:34
-	1077	((313/500,505,498).CCLS.)) and (TFT or thin\$film\$transistor)	USPAT	2004/05/12 09:07
-	919	(345/44,45,46,55,76).CCLS.	USPAT	2004/05/11 07:34
-	154	((313/501,502,503,504,506-512).CCLS.) or	USPAT	2004/05/11 08:08
-	1827	((313/500,505,498).CCLS.)) and (TFT or (thin\$ adj film\$ adj	USPAT	2004/05/11 08:08
-	1539	transistor\$))	USPAT	2004/05/11 08:08
-	37	((257/99-103).CCLS.) not	USPAT	2004/05/11 09:10
-	2	((313/501,502,503,504,506-512).CCLS.) or	USPAT	2004/05/11 09:12
-	1	((313/500,505,498).CCLS.) or ((345/44,45,46,55,76).CCLS.))	USPAT	2004/05/11 09:13
-	1	((257/99-103).CCLS.) not	USPAT	2004/05/11 09:15
-	6976	((313/501,502,503,504,506-512).CCLS.) or	USPAT;	2004/05/11 09:15
-	1620	((313/500,505,498).CCLS.)) and (TFT or (thin\$ adj film\$ adj transistor\$))	US-PGPUB	2004/05/11 09:15
-	560	((("5990629") or ("6641933")).PN.	US-PGPUB	2004/05/11 09:53
-	4108	("6611108").PN.	USPAT	2004/05/11 18:14
-	1	("6714268").PN.	USPAT	2004/05/11 18:14
-	7	yamazaki.in.	USPAT	2004/05/12 08:30
-	2027	yamazaki.in.	USPAT	2004/05/12 09:01
-	28	yamazaki.in. and TFT	USPAT	2004/05/12 09:05
-	72	349/\$.ccls. and TFT	USPAT	2004/05/12 09:04
-	1077	("5962959").PN.	USPAT	2004/05/12 09:06
-	40	("5990629").PN.	USPAT	2004/05/12 09:07
-	7	("5193017" "5327268" "5408345" "5426526" "5777696"	USPAT	2004/05/12 09:15
-	1	"5786242" "5805252").PN.	USPAT	2004/05/12 09:11
-	28	((313/501,502,503,504,506-512).CCLS.) not	USPAT	2004/05/12 09:17
-	72	((313/500,505,498).CCLS.)	USPAT	2004/05/12 09:17
-	1077	(313/500,505,498).CCLS. and TFT and resin	USPAT	2004/05/12 09:17
-	40	((313/501,502,503,504,506-512).CCLS.) and TFT and resin	USPAT	2004/05/12 16:12
-	7	(345/44,45,46,55,76).CCLS.		
-	1	((345/44,45,46,55,76).CCLS.) and TFT and resin		
-	1	("5193017" "5327268" "5408345" "5426526" "5777696"		
-	1	"5786242" "5805252").PN.		
-	1	5990629.pn. and resin.		
-	1	5990629.pn. and EL		
-	1	("6225966").PN.		
-	1	("6225966").PN.) and EL		